

1200V N-Channel Silicon Carbide Power MOSFET



1. Applications

- Asymmetrical Bridge Converter
- Inverter
- Single Switch Forward Flyback



2. Features

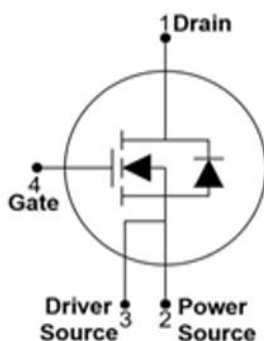
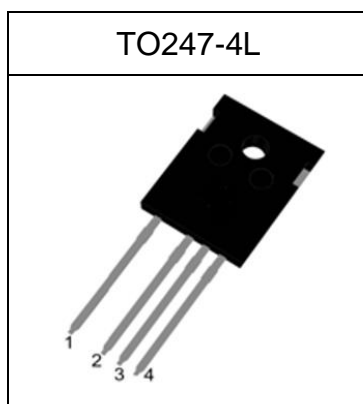
- Low drain-source on-resistance: $R_{DS(ON)} = 80m\Omega$ (typ.)
- Easy to control Gate switching
- Enhancement mode: $V_{th} = 2$ to 4 V

Table 1 Key Performance Parameters

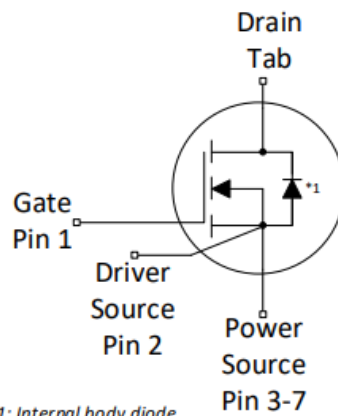
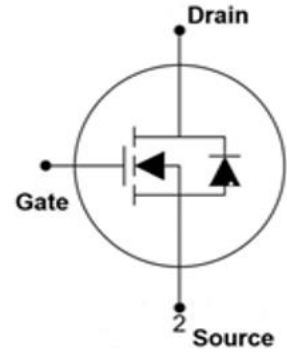
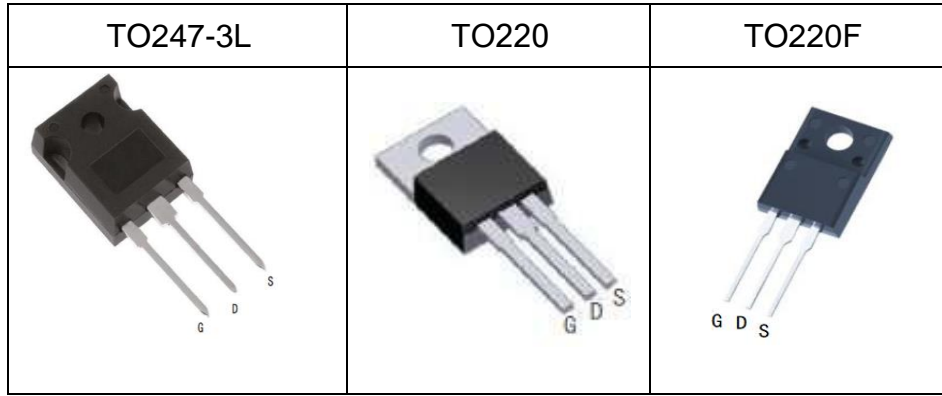
Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	1200	V
$R_{DS(on),max}$	100	m Ω
$Q_{g,typ}$	58	nC
$I_{D,pulse}$	94	A

3. Packaging and Internal Circuit

Part Name	Package	Marking
ADQ120N080G2	TO-247-4L	ADQ120N080G2
ADW120N080G2	TO-247-3L	ADW120N080G2
ADG120N080G2	TO-263-7L	ADG120N080G2
ADP120N080G2	TO-220	ADP120N080G2
ADA120N080G2	TO-220F	ADA120N080G2



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1 Maximum ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D	-	-	35	A	$T_C=25^\circ\text{C}$
		-	-	26	A	$T_C=100^\circ\text{C}$
Avalanche energy, single pulse	E_{AS}	-	-	200	mJ	$T_C=25^\circ\text{C}, V_{DD}=50\text{V}, L=1\text{mH}, R_G=25\Omega$
Gate source voltage (static)	V_{GS}	-5	-	20	V	static;
Power dissipation	P_{tot}	-	-	188	W	$T_C=25^\circ\text{C}$
Derating factor above 25°C		-	-	1.9	$\text{W}/^\circ\text{C}$	
Storage temperature	T_{stg}	-55	-	175	$^\circ\text{C}$	
Operating junction temperature	T_j	-55	-	175	$^\circ\text{C}$	
Soldering Temperature Distance of 1.6mm from case for 10s	T_L			300	$^\circ\text{C}$	
Transconductance	GFS	-	8.33	-	S	$V_{DS}=20\text{V } I_{DS}=20\text{A}$
			7.14			$V_{DS}=20\text{V } I_{DS}=20\text{A}, T_j=150^\circ\text{C}$

¹⁾Limited by $T_{j,max}$. Maximum Duty Cycle $D = 0.50$

²⁾Pulse width t_p limited by $T_{j,max}$

³⁾Identical low side and high side switch with identical R_G

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2 Thermal characteristics

Table 3 Thermal characteristics

TO247&TO220

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	0.65	0.8	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	40	°C/W	device on PCB, minimal footprint

TO263-7L

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	1.0	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	°C/W	device on PCB, minimal footprint

TO220F

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	5	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	60	°C/W	device on PCB, minimal footprint

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3 Electrical characteristics

at $T_j=25^\circ\text{C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	1200	-	-	V	$V_{GS}=0V, I_D=1mA$
Gate threshold voltage	$V_{(GS)th}$	2.0	2.8	4.0	V	$V_{DS}=V_{GS}, I_D=10mA$
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	$V_{DS}=1200V, V_{GS}=0V$
Gate-source leakage current	I_{GSS+}	-	-	100	nA	$V_{GS}=20V, V_{DS}=0V$
Gate-source leakage current	I_{GSS-}	-	-	-100	nA	$V_{GS}=-5V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	80	100	$m\Omega$	$V_{GS}=20V, I_D=20A, T_j=25^\circ\text{C}$
			93.1			$V_{GS}=20V, I_D=20A, T_j=150^\circ\text{C}$
Gate resistance (Intrinsic)	R_G	-	4.5	-	Ω	$f=1MHz, \text{open drain}$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	1377	-	pF	$V_{GS}=0V, V_{DS}=1000V, f=200KHz$
Output capacitance	C_{oss}	-	62	-	pF	$V_{GS}=0V, V_{DS}=1000V, f=200KHz$
Reverse transfer capacitance	C_{rss}	-	4	-	pF	$V_{GS}=0V, V_{DS}=1000V, f=200KHz$
Turn-on delay time	$t_{d(on)}$	-	10	-	ns	$V_{DD}=800V, V_{GS}=20V, I_D=20A, R_G=0\Omega; T_j=25^\circ\text{C}$
Rise time	t_r	-	6	-	ns	
Turn-off delay time	$t_{d(off)}$	-	16	-	ns	
Fall time	t_f	-	10	-	ns	
Turn-on Switching Energy	E_{on}		748.8		μJ	
Turn-off Switching Energy	E_{off}		31.2		μJ	

Table 6 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	18	-	nC	$V_{DD}=800V, I_D=20A, V_{GS}=20V$
Gate to drain charge	Q_{gd}	-	17	-	nC	$V_{DD}=800V, I_D=20A, V_{GS}=20V$
Gate charge total	Q_g	-	58	-	nC	$V_{DD}=800V, I_D=20A, V_{GS}=20V$

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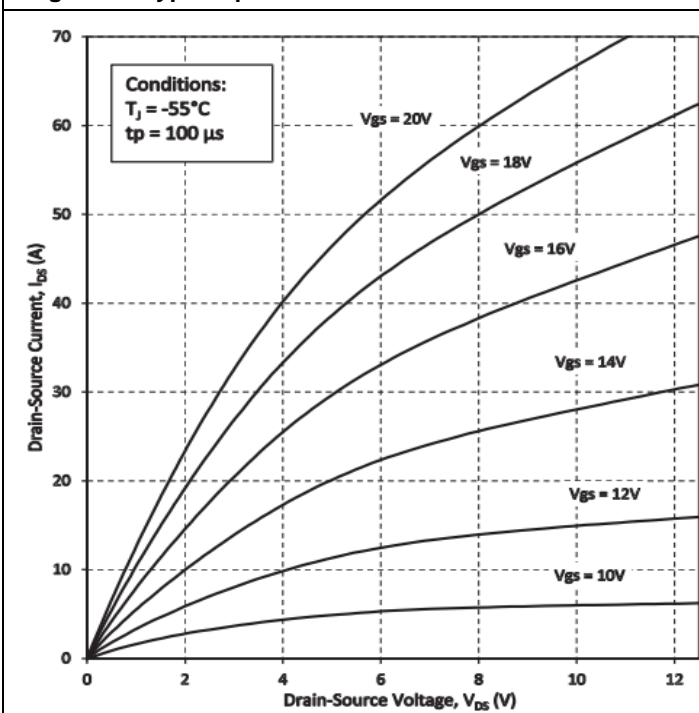
Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous Source Current	I_{SD}	-	-	35	A	
Diode forward voltage	V_{SD}	-	3.8	-	V	$I_S=10A, V_{GS}=0V, T_j=25^\circ C$
Reverse recovery time	t_{rr}	-	57	-	ns	$V_{DD}=800V, I_D=20A, +V_{GS}=+15V,$
Reverse recovery charge	Q_{rr}	-	195	-	nC	$-V_{GS}=-4V$ $di/dt=1000A/\mu s$
Peak reverse recovery current	I_{rrm}	-	6.84	-	A	$L_{Load}=500\mu H, R_g=0\Omega, T_j=25^\circ C$

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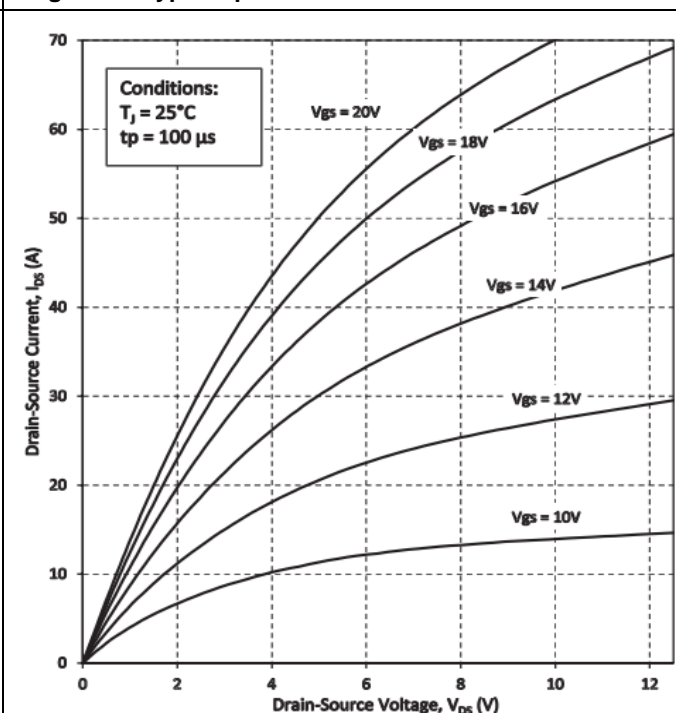
4 Electrical characteristics diagram

Diagram 1: Typ. output characteristics



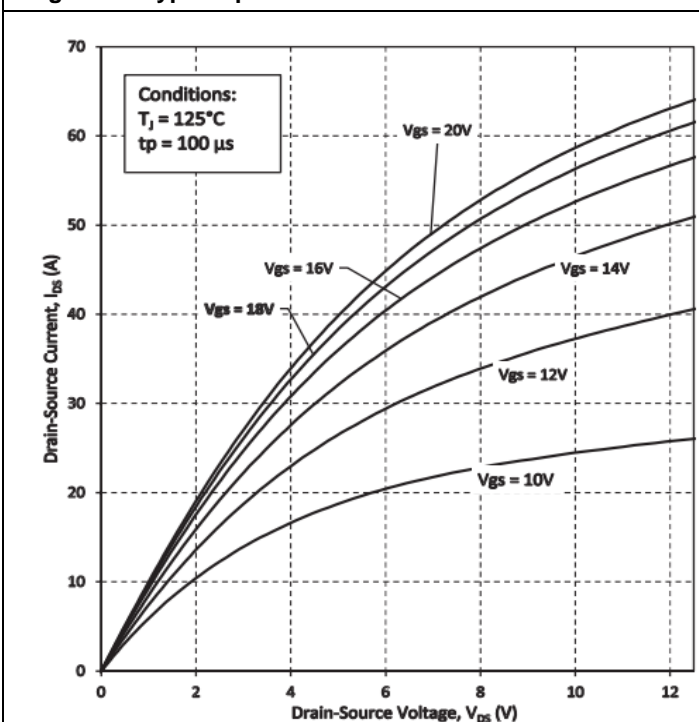
$I_D = f(V_{DS}); T_J = -55^\circ\text{C};$ parameter: V_{GS}

Diagram 2: Typ. output characteristics



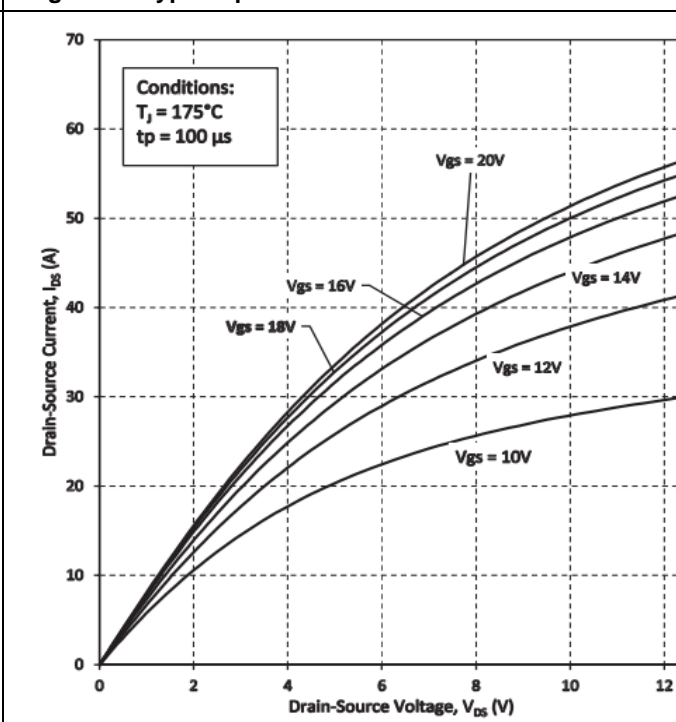
$I_D = f(V_{DS}); T_J = 25^\circ\text{C};$ parameter: V_{GS}

Diagram 3: Typ. output characteristics



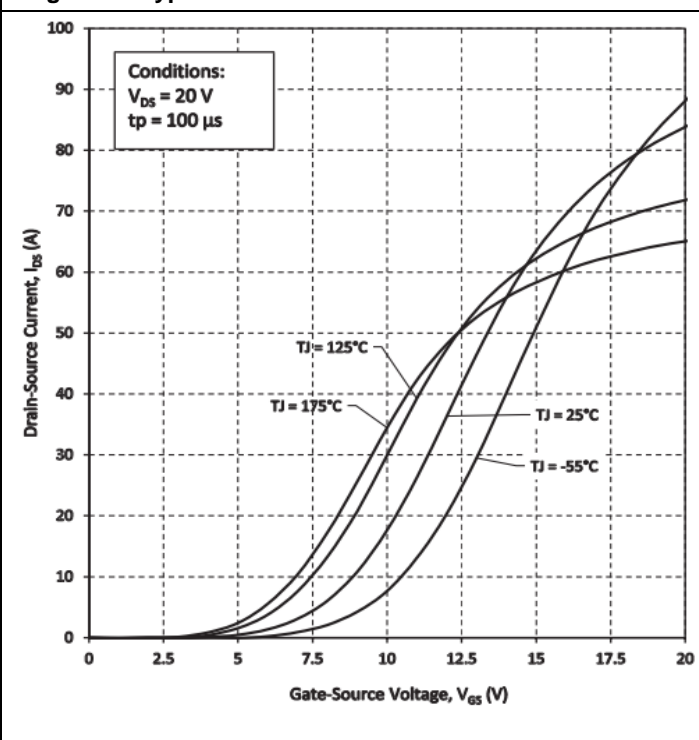
$I_D = f(V_{DS}); T_J = 125^\circ\text{C};$ parameter: V_{GS}

Diagram 4: Typ. output characteristics



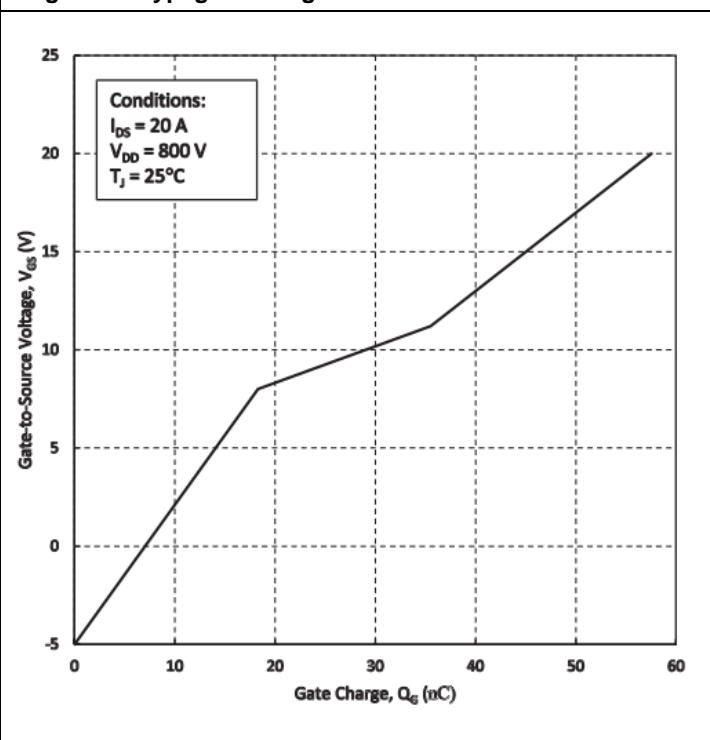
$I_D = f(V_{DS}); T_J = 175^\circ\text{C};$ parameter: V_{GS}

Diagram 5: Typ. transfer characteristics



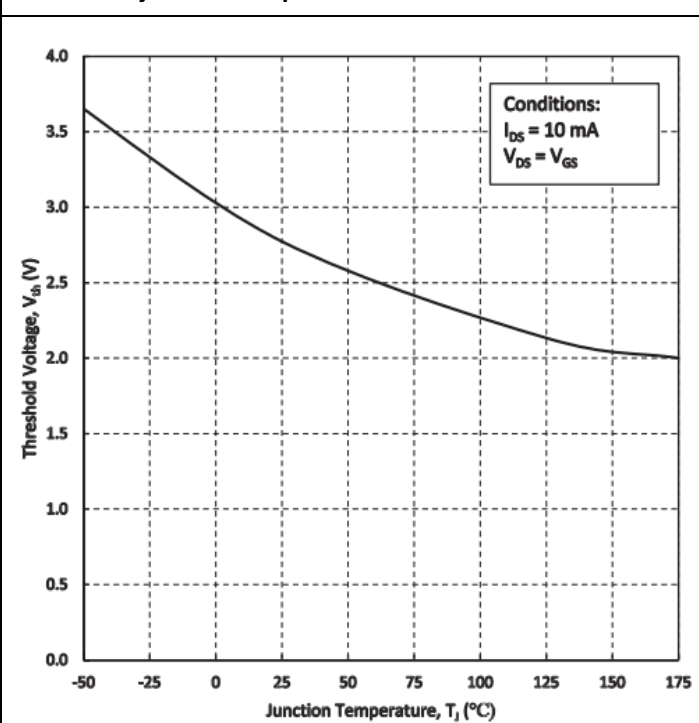
$I_D = f(V_{GS})$; $V_{DS} = 20\text{V}$; parameter: T_j

Diagram 5: Typ. gate charge



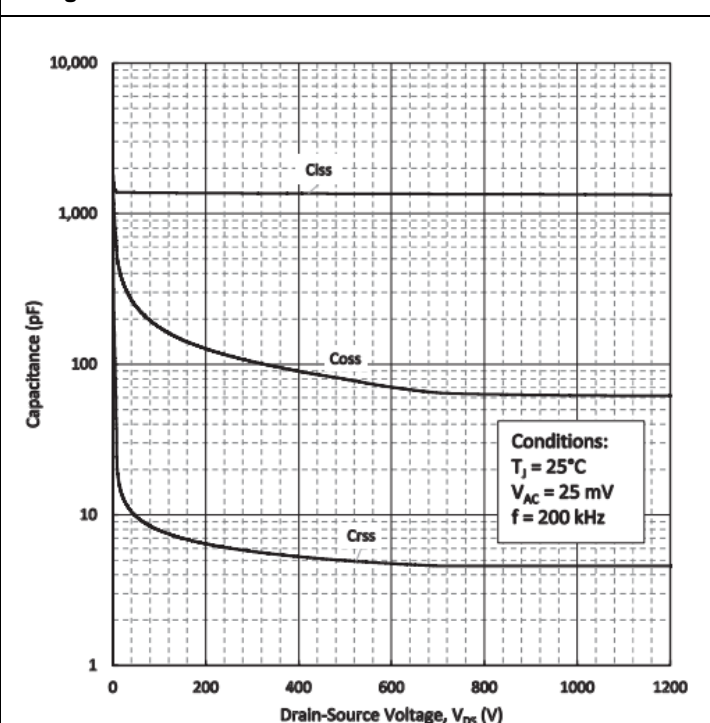
$V_{GS} = f(Q_{gate})$; $I_D = 20\text{A}$; $V_{DS} = 800\text{V}$; turn-on pulse

Diagram 7: Typical gate-source threshold voltage as a function of junction temperature



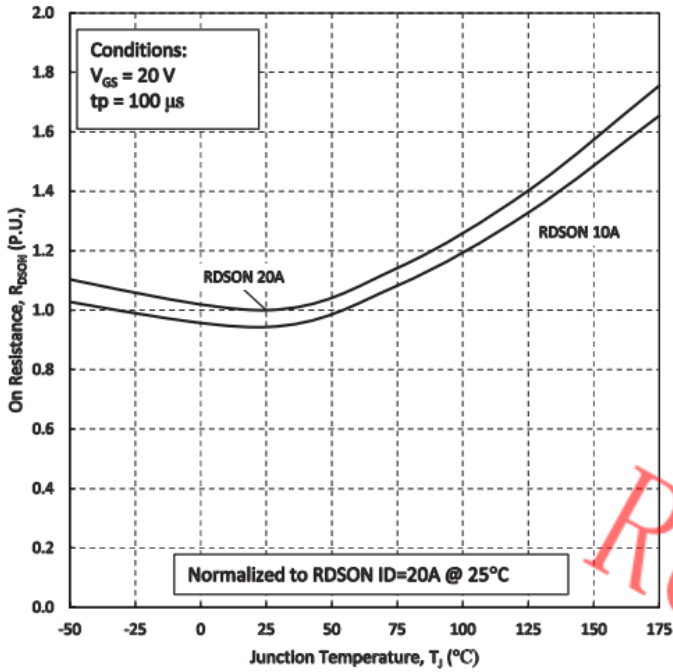
$V_{GS(th)} = f(T_j)$; $I_{DS} = 10\text{mA}$; $V_{GS} = V_{DS}$

Diagram 8: Typ. Capacitance as a function of drain-source voltage



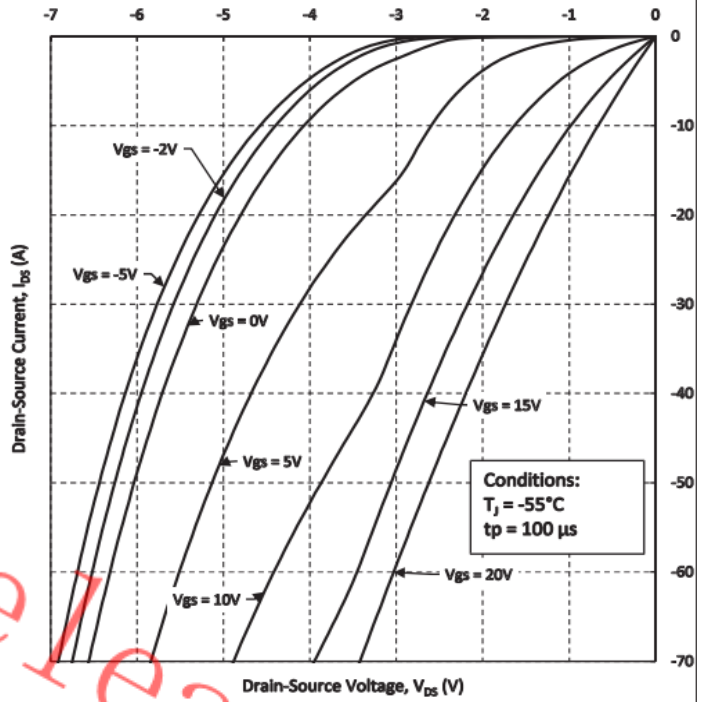
$C = f(V_{DS})$; $V_{GS} = 0\text{V}$; $f = 200\text{KHz}$

Diagram 9: Normalized on-resistance as a function of junction temperature



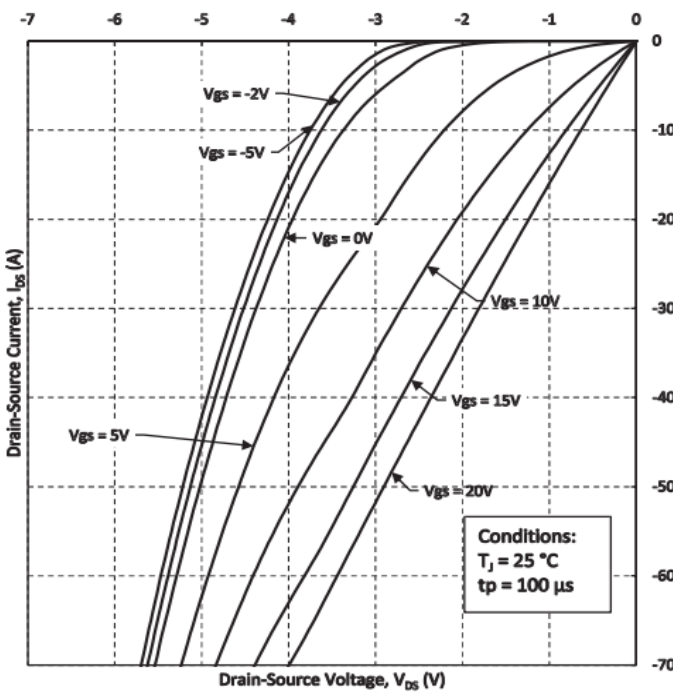
$R_{DS(ON)}=f(T_j); I_{DS}=20A$

Diagram 10: Typical Body Diode Characteristics at $T_j=-55^\circ C$



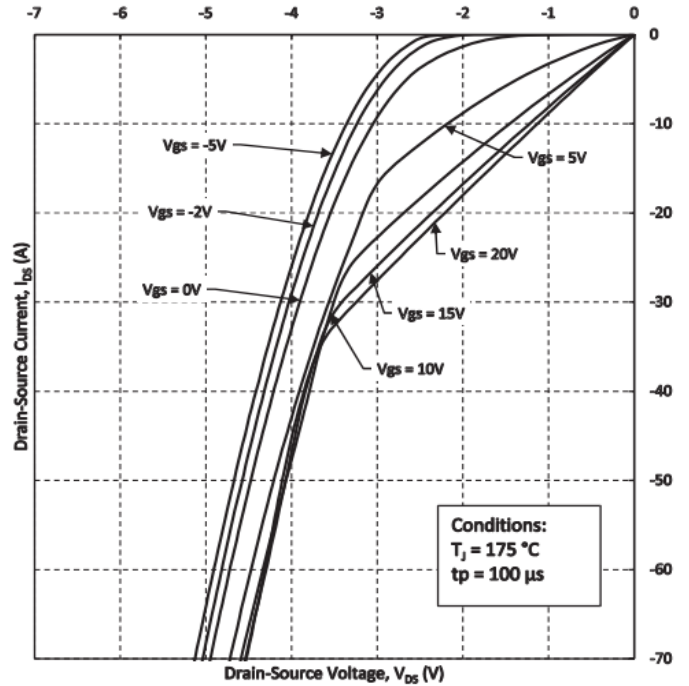
$I_{SD}=f(V_{SD}); T_j=-55^\circ C$

Diagram 11: Typical Body Diode Characteristics at $T_j=25^\circ C$



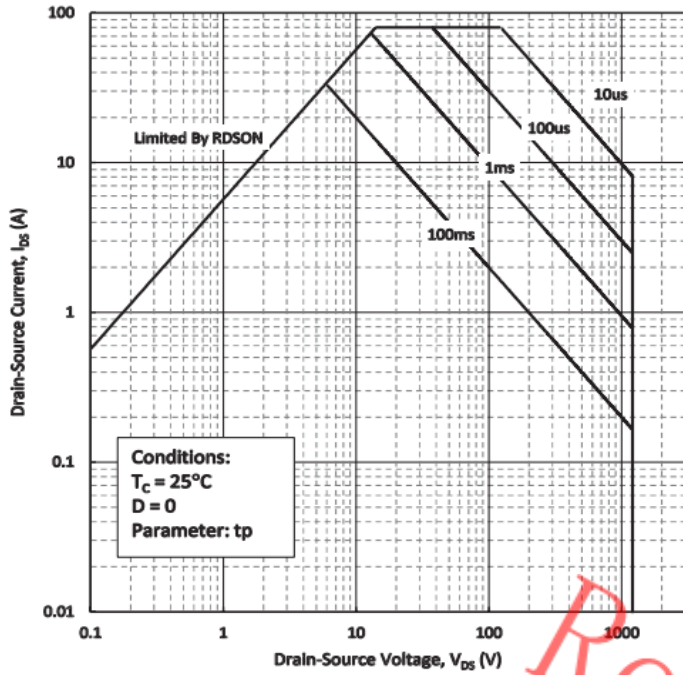
$I_{SD}=f(V_{SD}); T_j=25^\circ C$

Diagram 12: Typical Body Diode Characteristics at $T_j=175^\circ C$



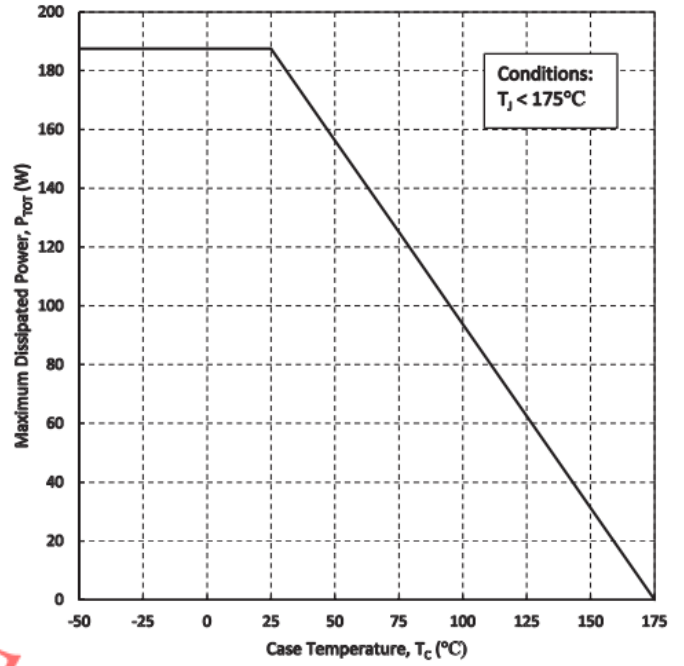
$I_{SD}=f(V_{SD}); T_j=175^\circ C$

Diagram 13: Safe operating area(SOA)



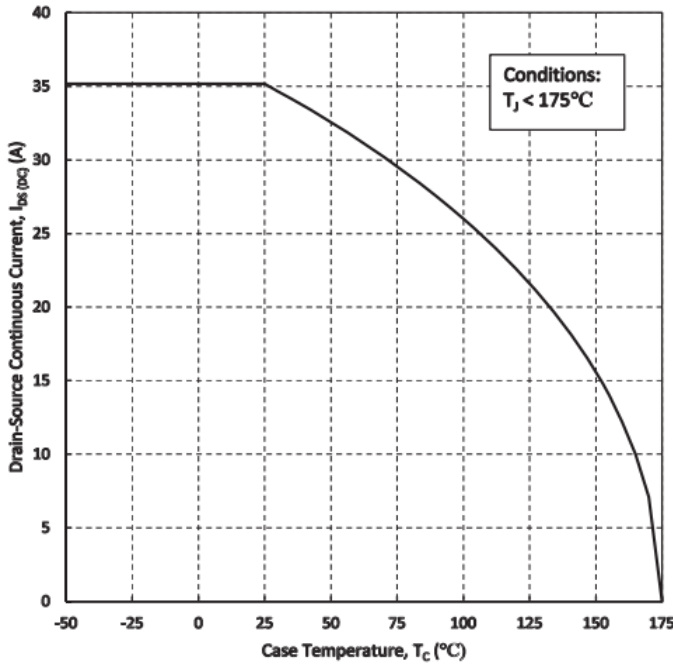
$V_{GS}=0/18V$; $T_C=25^\circ C$; $T_J<175^\circ C$

Diagram 14: Power dissipation as a function of case temperature limited by bond wire



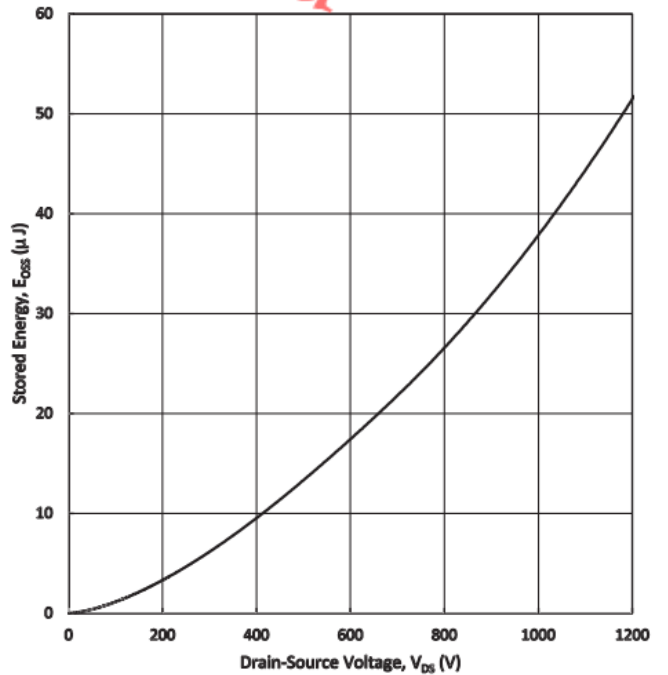
$P_{tot}=f(T_C)$

Diagram 15: Continuous Drian Current Derating vs. Case Temperature



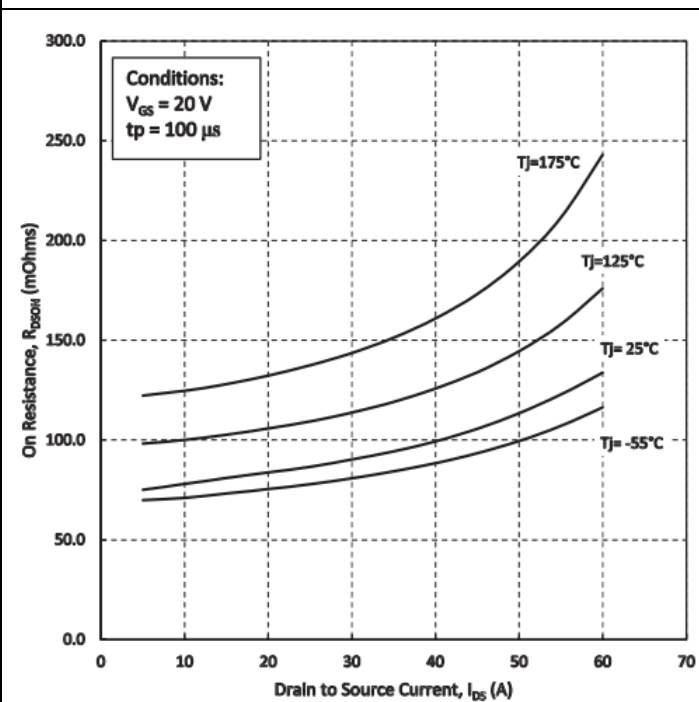
$I_{DS}=f(T_C)$

Diagram 16: Output Capacitor Stored Energy



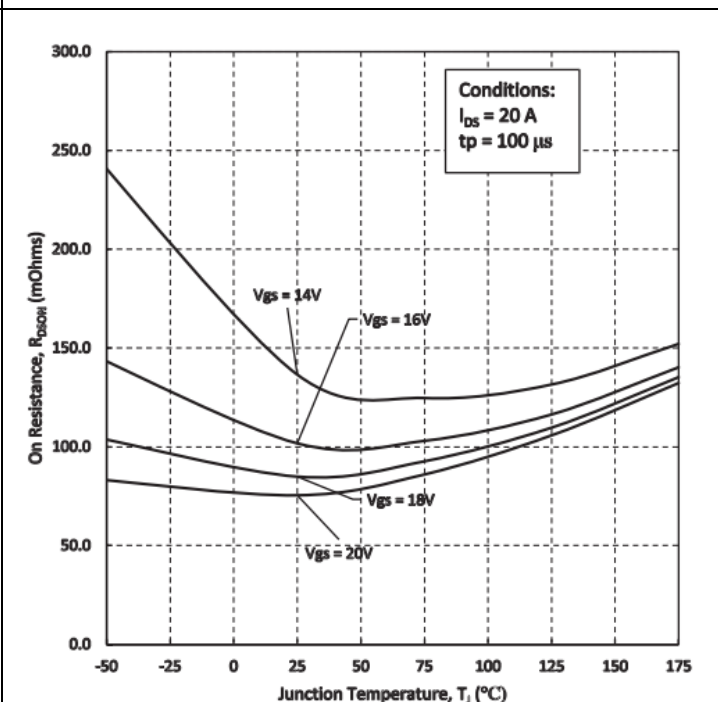
$E_{oss}=f(V_{DS})$

Diagram 17: On-Resistance vs. Drain Current For Various Temperature



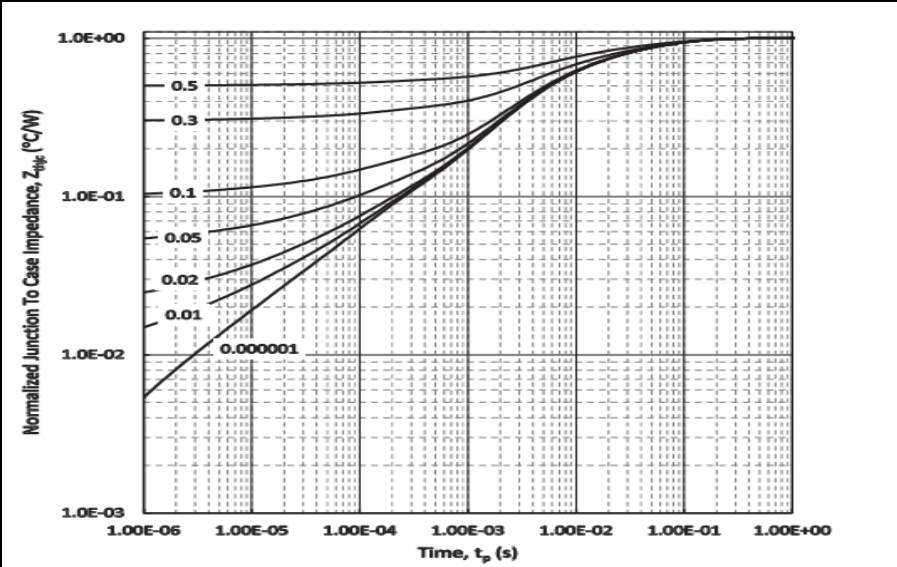
$R_{DS(ON)} = f(T_J); I_{DS} = 20\text{ A}$

Diagram 18: On-Resistance vs. Temperature For Various Gate Voltages



$R_{DS(ON)} = f(T_J); I_{DS} = 20\text{ A}$

Diagram 19: Max. transient thermal resistance(MOSFET/diodes)



$Z_{th(j-c,max)} = f(t_p), \text{parameter } D = t_p/T$

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5 Test Circuits

Table 8 Diode characteristics

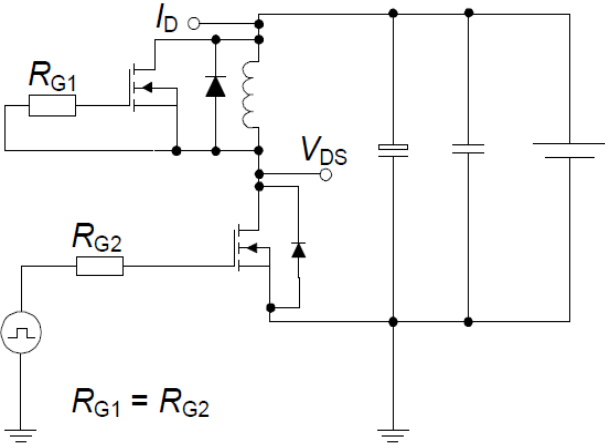
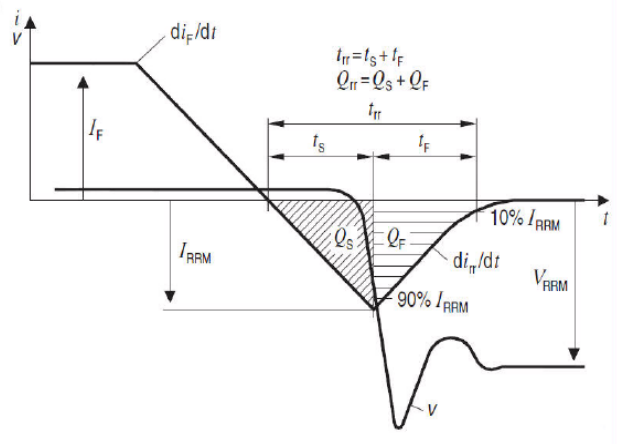
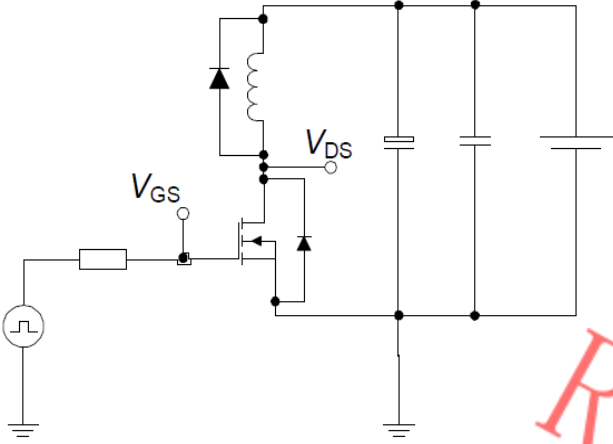
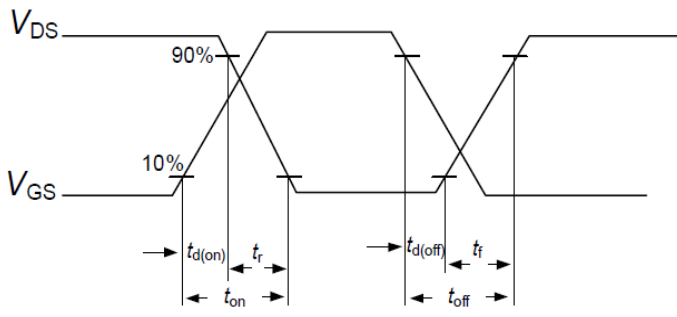
Test circuit for diode characteristics	Diode recovery waveform
 <p style="text-align: center;">$R_{G1} = R_{G2}$</p>	

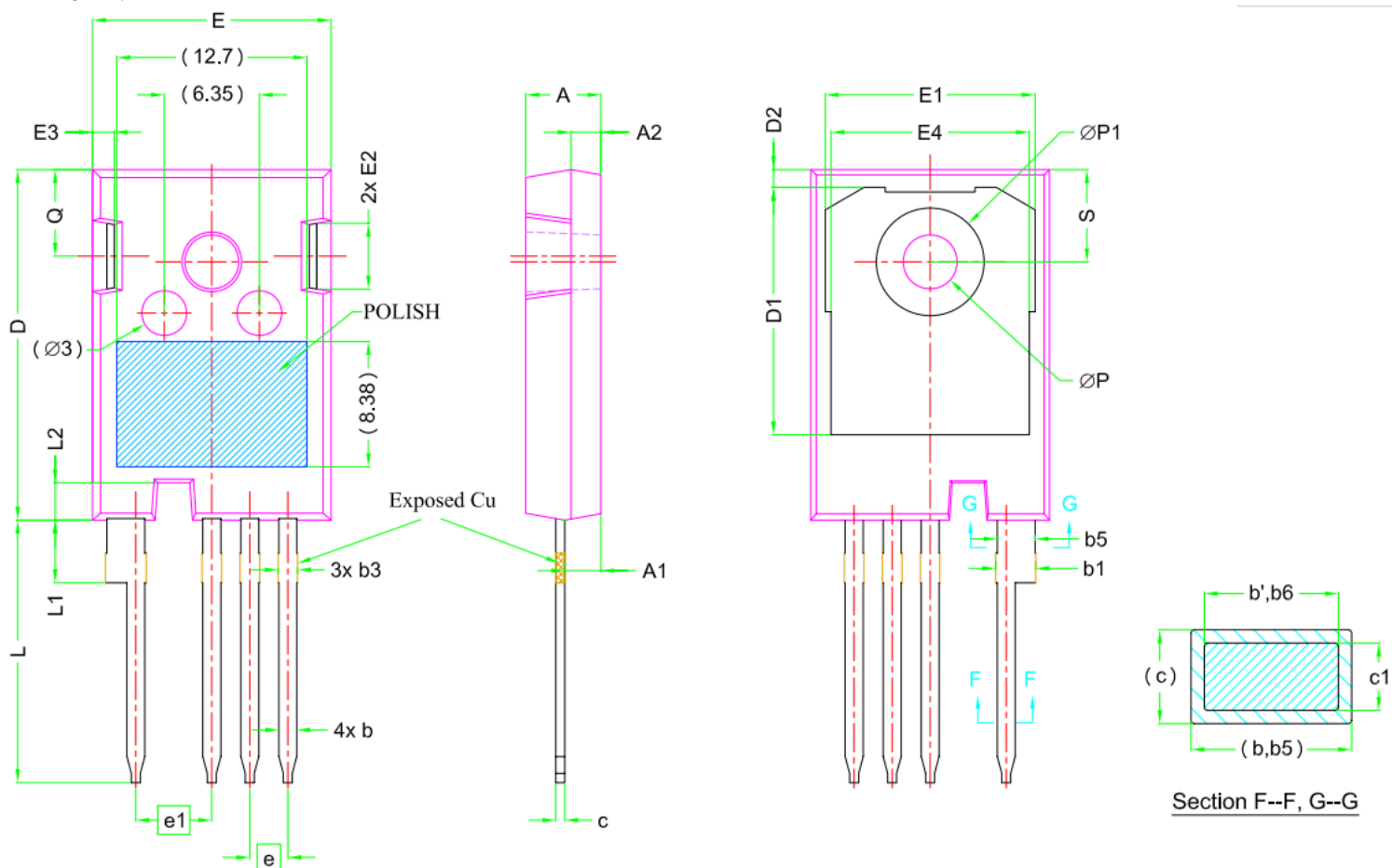
Table 9 Switching times

Switching times test circuit for inductive load	Switching times waveform
	

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6 Package Outlines

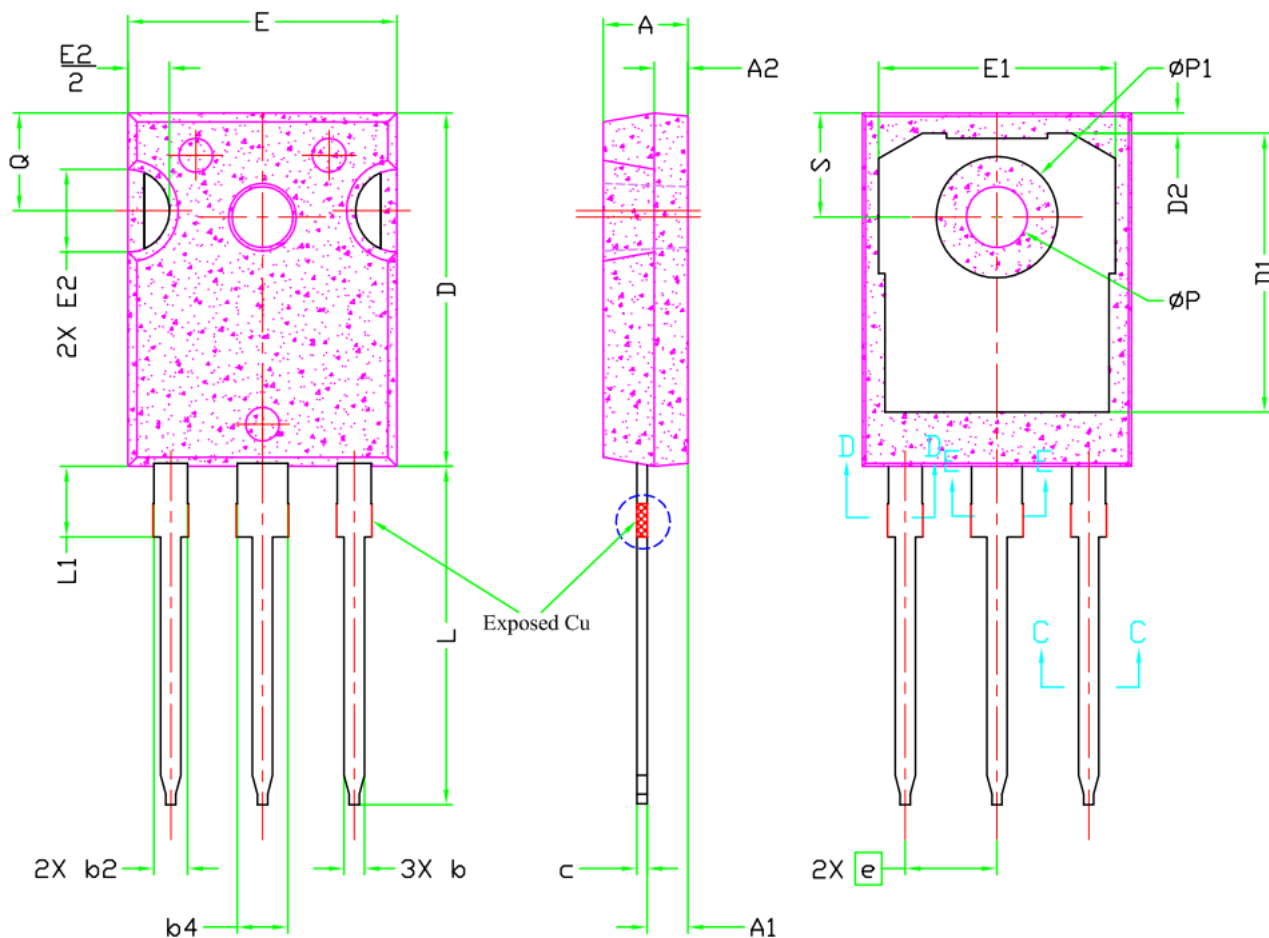
TO-247-4L



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.83	5.02	5.21
A1	2.29	2.41	2.54
A2	1.91	2.00	2.16
b'	1.07	1.20	1.28
b	1.07	1.20	1.33
b1	2.39	2.67	2.94
b3	1.07	1.30	1.60
b5	2.39	2.53	2.69
b6	2.39	2.53	2.64
c	0.55	0.60	0.68
c1	0.55	0.60	0.65
D	23.30	23.45	23.60
D1	16.25	16.55	17.65
D2	0.95	1.19	1.25
E	15.75	15.94	16.13
E1	13.10	14.02	14.15
E2	3.68	4.40	5.10
E3	1.00	1.45	1.90
E4	12.38	13.26	13.43
e	2.54 BSC		
e1	5.08 BSC		
L	17.31	17.57	17.82
L1	3.97	4.19	4.37
L2	2.35	2.50	2.65
$\text{Ø}P$	3.51	3.61	3.65
$\text{Ø}P1$	7.19 REF.		
Q	5.49	5.79	6.00
S	6.04	6.17	6.30

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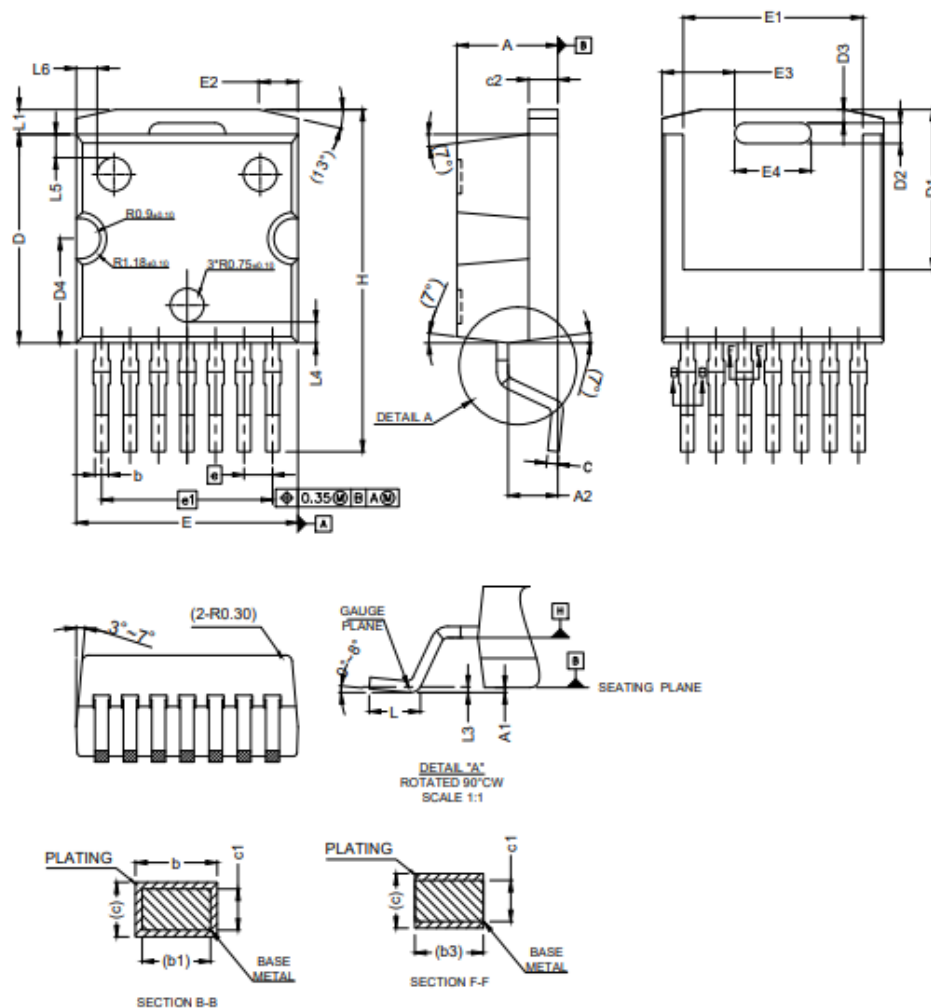
TO-247-3L



SYMBOL	DIMENSIONS			NOTES
	MIN.	NOM.	MAX.	
A	4.83	5.02	5.21	
A1	2.29	2.41	2.55	
A2	1.50	2.00	2.49	
b	1.12	1.20	1.33	
b1	1.12	1.20	1.28	
b2	1.91	2.00	2.39	6
b3	1.91	2.00	2.34	
b4	2.87	3.00	3.22	6, 8
b5	2.87	3.00	3.18	
c	0.55	0.60	0.69	6
c1	0.55	0.60	0.65	
D	20.80	20.95	21.10	4
D1	16.25	16.55	17.65	5
D2	0.51	1.19	1.35	
E	15.75	15.94	16.13	4
E1	13.46	14.02	14.16	5
E2	4.32	4.91	5.49	3
e	5.44BSC			
L	19.81	20.07	20.32	
L1	4.10	4.19	4.40	6
∅P	3.56	3.61	3.65	7
∅P1	7.19REF.			
Q	5.39	5.79	6.20	
S	6.04	6.17	6.30	

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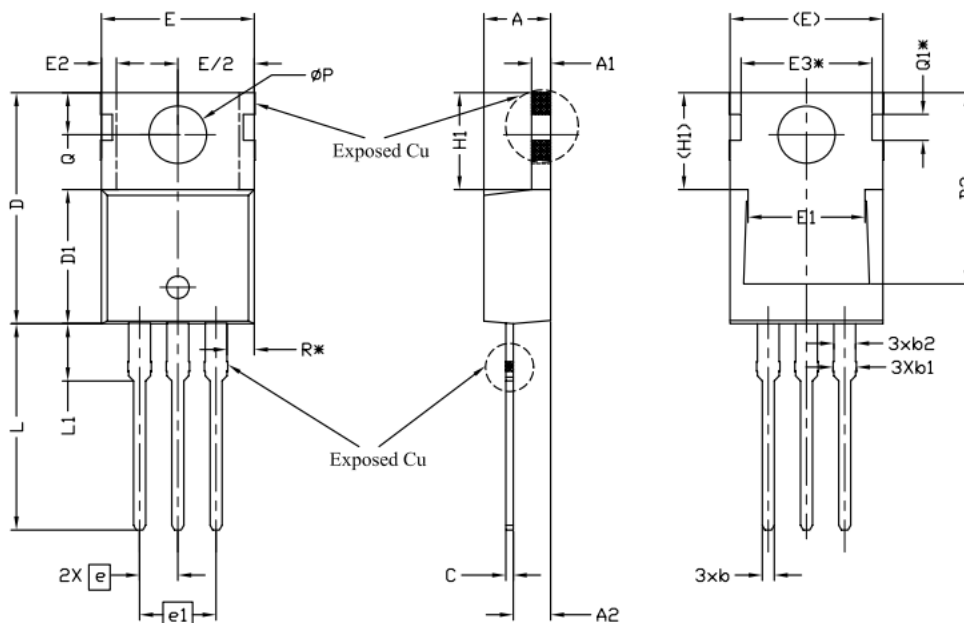
TO-263-7L (RYX&HY)



SYMBOL	MIN	MAX	SYMBOL	MIN	MAX
A	4.3	4.7	L	1.78	2.79
A1	-	0.25	L1	-	1.6
A2	2.02	2.75	L3	0.25BSC	
b	0.5	0.7	L4	0.93BSC	
b1	0.5	0.65	L5	1.04BSC	
b3	0.6	0.75	L6	0.93BSC	
c	0.45	0.6	H	14.61	16
c1	0.45	0.55			
c2	1.25	1.4			
D	8.93	9.5			
D1	6.86	7.42			
D2	0.72	1.12			
D3	0.4	0.8			
D4	4.45	4.85			
E	9.68	10.28			
E1	6.82	8.3			
E2	1.55	1.95			
E3	3.04	3.44			
E4	3.21	3.61			
e	1.27 BSC				
e1	7.62 BSC				

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TO-220



SYMBOL	DIMENSIONS			NOTES
	MIN.	NOM.	MAX.	
A	4.24	4.44	4.64	
A1	1.15	1.27	1.40	
A2	2.30	2.48	2.70	
b	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
c	0.40	0.50	0.60	
D	14.70	15.37	16.00	4
D1	8.82	8.92	9.02	
D2	12.43	12.73	12.83	5
E	9.96	10.16	10.36	4,5
E1	6.86	7.77	8.89	5
E2	-	-	0.76	6
E3*	8.70REF.			
e	2.54BSC			
e1	5.08BSC			
H1	6.30	6.45	6.60	5,6
L	13.47	13.72	13.97	
L1	3.60	3.80	4.00	
øP	3.75	3.84	3.93	
Q	2.60	2.80	3.00	
Q1*	1.73REF.			
R*	1.82REF.			

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Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2022-05-27	Preliminary version
1.1	2023-04-06	Updated TO263-7L POD include RYX&HY
1.2	2023-09-05	Updated some Electrical characteristics diagram
1.3	2024-03-19	Add package for TO220 and TO220F

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[GC3M0021120K](#) [SP25N120CTK](#) [SP90N120CTK](#) [GC3M0080120K](#) [SP50N120CTK](#) [GC2M0160120D](#) [GC2M1000170D](#) [GC3M0120100K](#)
[GC2M0080120D](#) [SP50N120CTF](#) [SP35N120CTF](#) [SP25N120CTF](#) [IV2Q171R0D7](#) [IV1Q06040L1](#) [IV1Q06060T3G](#) [IV1Q12160T4](#)
[IV1B12013HA1L](#) [IV1Q12160T3](#) [IV1Q07015T4G](#) [IV1Q12750O3](#) [IV1Q06040T3](#) [IV1Q12050T4Z](#) [IV1Q12030T4G](#)